

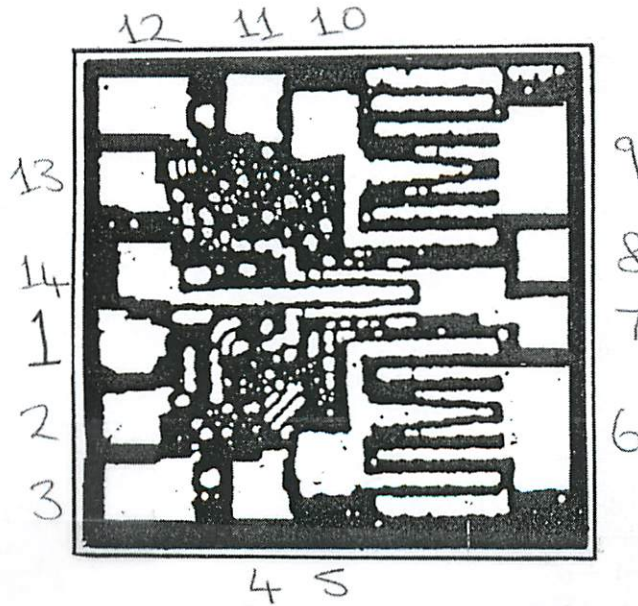


# Sierra Components, Inc.

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Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.



<u>Pad</u>	<u>Function</u>	<u>Pad</u>	<u>Function</u>
1	G	8	SUB
2	1A	9	2E
3	1Y	10	2C
4	1B	11	2B
5	1C	12	2Y
6	1E	13	2A
7	GND	14	V <sub>cc</sub>

**Top Material: Al**  
**Backside Material: Si**  
**Bond Pad Size: .004" X .004"**  
**Backside Potential:**  
**Mask Ref:**

APPROVED BY: \_\_\_\_\_

DIE SIZE .046" X .051"

DATE: 3/8/12

MFG: TEXAS INSTRUMENTS

THICKNESS .015"

P/N: SN55450B